

Focus on: Development

Hardware

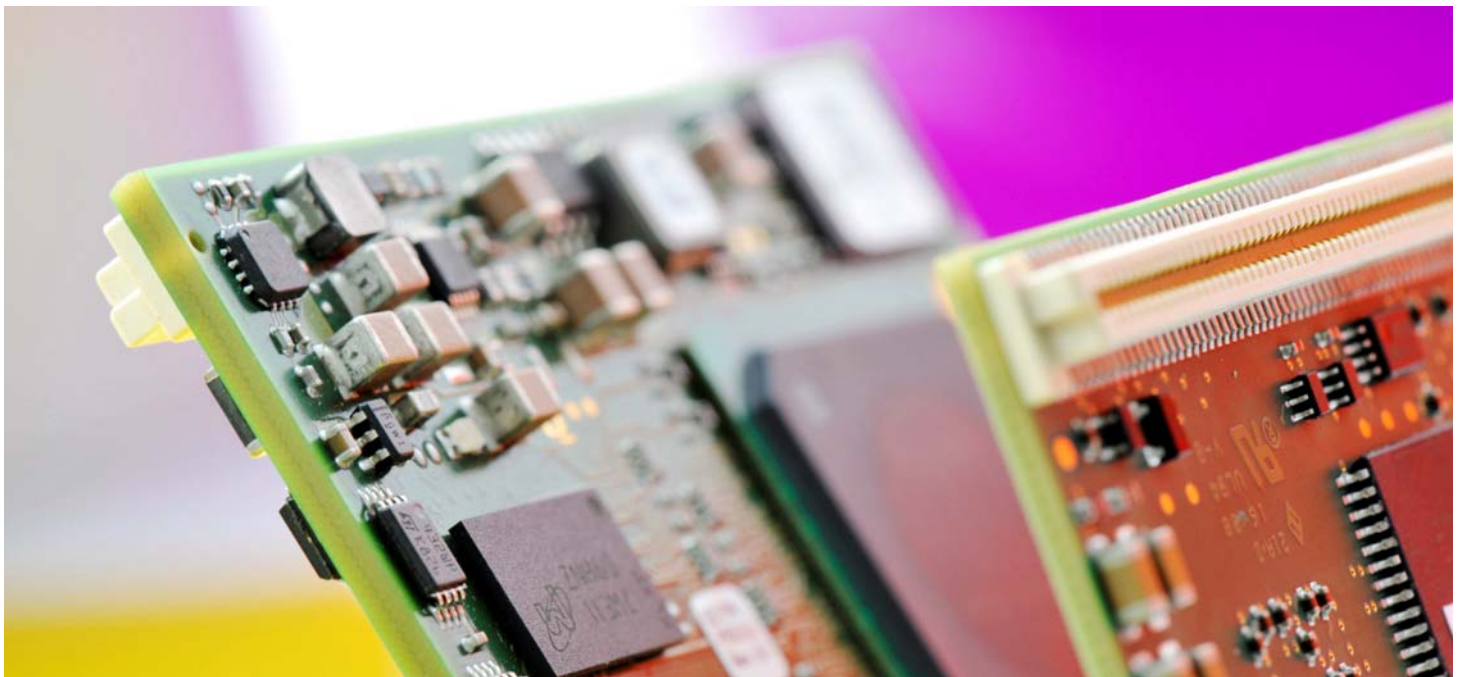
- Power electronics
 - power supply
 - DC/DC converter
 - DC/AC converter
 - motor controls (Stepp motors, brush-type/ brush-free DC motors)
- Measurement engineering
 - analog measurement engineering
 - infrared measurement
 - digital signal processing
 - optoelectronics
- HF technology/radio technology
 - ISM
 - GSM, GPRS, UMTS
 - WLAN
 - Bluetooth
 - ZigBee
- Microcontroller technology
 - 8 Bit: Atmel AVR, PIC, Z8, 8051 family
 - 16 Bit: Infineon C166 family, Infineon SC166 family, Toshiba CP32 family, Renesas H8
 - 32/64 Bit: Cortex-M3, ColdFire, Infineon TriCore, ARM7/9, Freescale PPC PowerQUICC I – III, QorIQ, x86 family, Intel/AMD/VIA
 - interfaces/fieldbusses: PCI/PCI Express, ISA, PC-Card, USB, FireWire, RS232/RS485/RS422, CAN, LON, ASI, Profi Bus, M-Bus, Ethernet, ...
- Display technologies
 - customer specific displays
 - display controls (TN/STN, TFT, VFD)
- Simulation
 - digital, analog, HF, Timing
 - programs: HyperLynx Line-sim/Boardsim, SynaptiCAD Timing Diagrammer

Software

- Firmware development
 - BIOS / bootlader / monitor
 - customer-/hardware-specific embedded applications
- Operating system adjustments (PowerPC, ARM, x86)
 - Embedded Linux
 - Windows, Windows CE
 - FreeRTOS
 - VxWorks
 - QNX
- Device driver
 - CAN, CANopen, Modbus
 - USB, RS232/RS485, FireWire
 - Ethernet
 - PCI/PCI Express
 - camera interface (CSI)
- applications with user interface (Qt, GTK, MPEG)

Logic design / System-on-Chip development

- Application examples
 - image processing - performant algorithm implementation
 - microcontroller - highly flexible peripheral expansion
 - power electronics - fast control systems and feedback systems
 - communication – customized for throughput, latency, protocol
- Design
 - selection and integration of 3rd party IP
 - use of highly complex system components (e. g. embedded processors, high-speed I/Os)
 - verification by simulation and hardware tests
- Architectures
 - implementation in all commonly used FPGA and CPLD components (e. g. Xilinx, Altera, Lattice, Actel)
- FPGA conversion to ASIC



Layout

- flexible and starr-flex PCB
- multilayer (up to 32 layers)
- impedance-controlled layouts
- design for testability
- design for production
- microvia technology
- blind hole technology
- buried via technology
- programs: Integra Station, Specctra Autorouter, PADS, Protel 99SE/Altium Designer, Expedition Enterprise, Design-Capture, DxDesigner

Testing tool development / test equipment

- test concept / DFT
- calculation of testing depths and error probabilities
- test software
- test models
- construction of test adapters and test devices
- maintenance and calibration of test equipment
- technologies
 - in-circuit test analog and digital
 - flying probe test
 - function test
 - boundary scan test
 - combi and cluster test
 - burn-in/run-in

Product qualification

- EMC/ESD/CE
 - interference resistance measurements (EN61000 4-4 - BURST, EN61000 4-5 - SURGE, EN61000 4-11 - DIPS, EN61000 4-2 - ESD)
 - interference emissions measurement (EN55011, EN61000 6-4, EN5522, EN61000 6-3)
- UL/CSA
- climate
- vibration and shock

- FMEA
- durability analysis, durability tests

Project management

- project planning
- project management
- project controlling
- target costing
- quality planning
- requirement management
- engineering change management
- product lifecycle management

Mechanics

- 3D construction (Autodesk Inventor Professional, AutoCAD Mechanical)
- simulation (Autodesk Inventor Professional, ICEPAK 12.0)
- mechanical design
- tools
 - cutting and shaping tools
 - plastic injection molding
 - die-cast aluminium
 - tools for process realization and optimization
- Prototyping/small-lot engineering
 - 3D printer
 - stereolithography
 - PU casting
 - CAM-based chipping techniques
 - sheet form techniques
 - surface machining
- testing

Contact

TQ-Group
 Gut Delling | Mühlstraße 2 | 82229 Seefeld | Germany
 Phone +49 8153 9308-0 | Fax +49 8153 4223
 info@tq-group.com | www.tq-group.com